

Thyristor Modules

Thyristor/Diode Modules

$$I_{TRMS} = 2 \times 180 \text{ A}$$

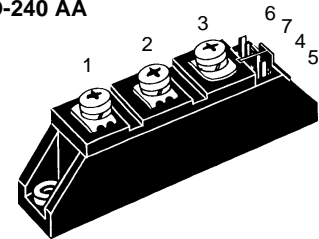
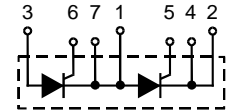
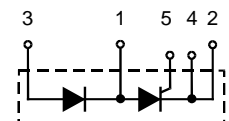
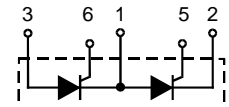
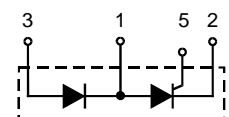
$$I_{TAVM} = 2 \times 116 \text{ A}$$

$$V_{RRM} = 800\text{-}1800 \text{ V}$$

V_{RSM} V_{DSM} V	V_{RRM} V_{DRM} V	Type	
		Version 1	Version 8
900	800	MCC 95-08io1 B	--
1300	1200	MCC 95-12io1 B	MCD 95-12io1 B
1500	1400	MCC 95-14io1 B	--
1700	1600	MCC 95-16io1 B	MCD 95-16io1 B
1900	1800	MCC 95-18io1 B	--
1500	1400	MCC 95-16io1	
1700	1600	MCC 95-18io1	

Symbol	Test Conditions	Maximum Ratings	
I_{TRMS} , I_{FRMS}	$T_{VJ} = T_{VJM}$	180	A
I_{TAVM} , I_{FAVM}	$T_C = 85^\circ\text{C}$; 180° sine	116	A
I_{TSM} , I_{FSM}	$T_{VJ} = 45^\circ\text{C}$; $V_R = 0$	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	2250 A 2400 A
	$T_{VJ} = T_{VJM}$	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	2000 A 2150 A
$\int i^2 dt$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0$	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	25 300 A ² s 23 900 A ² s
	$T_{VJ} = T_{VJM}$	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	20 000 A ² s 19 100 A ² s
$(di/dt)_{cr}$	$T_{VJ} = T_{VJM}$ f = 50 Hz, t _p = 200 μs $V_D = 2/3 V_{DRM}$ $I_G = 0.45 \text{ A}$ di _G /dt = 0.45 A/μs	repetitive, I _T = 250 A non repetitive, I _T = I _{TAVM}	150 A/μs 500 A/μs
$(dv/dt)_{cr}$	$T_{VJ} = T_{VJM}$; R _{GK} = ∞; method 1 (linear voltage rise)	$V_{DR} = 2/3 V_{DRM}$	1000 V/μs
P_{GM}	$T_{VJ} = T_{VJM}$ I _T = I _{TAVM}	t _p = 30 μs t _p = 300 μs	10 W 5 W
P_{GAV}			0.5 W
V_{RGM}			10 V
T_{VJ}			-40...+125 °C
T_{VJM}			125 °C
T_{sig}			-40...+125 °C
V_{ISOL}	50/60 Hz, RMS I _{ISOL} ≤ 1 mA	t = 1 min t = 1 s	3000 V~ 3600 V~
M_d	Mounting torque (M5) Terminal connection torque (M5)		2.5-4.0/22-35 Nm/lb.in. 2.5-4.0/22-35 Nm/lb.in.
Weight	Typical including screws		90 g

Data according to IEC 60747 and refer to a single thyristor/diode unless otherwise stated.
IXYS reserves the right to change limits, test conditions and dimensions

TO-240 AA

MCC
Version 1

MCD
Version 1

MCC
Version 8

MCD
Version 8


Features

- International standard package, JEDEC TO-240 AA
- Direct copper bonded Al₂O₃ -ceramic base plate
- Planar passivated chips
- Isolation voltage 3600 V~
- UL registered, E 72873
- Gate-cathode twin pins for version 1

Applications

- DC motor control
- Softstart AC motor controller
- Light, heat and temperature control

Advantages

- Space and weight savings
- Simple mounting with two screws
- Improved temperature and power cycling
- Reduced protection circuits

Symbol	Test Conditions	Characteristic Values
I_{RRM}, I_{DRM}	$T_{VJ} = T_{VJM}; V_R = V_{RRM}; V_D = V_{DRM}$	5 mA
V_T, V_F	$I_T, I_F = 300 \text{ A}; T_{VJ} = 25^\circ\text{C}$	1.5 V
V_{TO}	For power-loss calculations only ($T_{VJ} = 125^\circ\text{C}$)	0.8 V
r_T		2.4 mΩ
V_{GT}	$V_D = 6 \text{ V}; T_{VJ} = 25^\circ\text{C}$	2.5 V
	$T_{VJ} = -40^\circ\text{C}$	2.6 V
I_{GT}	$V_D = 6 \text{ V}; T_{VJ} = 25^\circ\text{C}$	150 mA
	$T_{VJ} = -40^\circ\text{C}$	200 mA
V_{GD}	$T_{VJ} = T_{VJM}; V_D = 2/3 V_{DRM}$	0.2 V
I_{GD}		10 mA
I_L	$T_{VJ} = 25^\circ\text{C}; t_p = 10 \mu\text{s}; V_D = 6 \text{ V}$ $I_G = 0.45 \text{ A}; di_G/dt = 0.45 \text{ A}/\mu\text{s}$	450 mA
I_H	$T_{VJ} = 25^\circ\text{C}; V_D = 6 \text{ V}; R_{GK} = \infty$	200 mA
t_{gd}	$T_{VJ} = 25^\circ\text{C}; V_D = 1/2 V_{DRM}$ $I_G = 0.45 \text{ A}; di_G/dt = 0.45 \text{ A}/\mu\text{s}$	2 μs
t_q	$T_{VJ} = T_{VJM}; I_T = 150 \text{ A}; t_p = 200 \mu\text{s}; -di/dt = 10 \text{ A}/\mu\text{s}$ typ. $V_R = 100 \text{ V}; dv/dt = 20 \text{ V}/\mu\text{s}; V_D = 2/3 V_{DRM}$	185 μs
Q_S	$T_{VJ} = T_{VJM}; I_T, I_F = 50 \text{ A}; -di/dt = 6 \text{ A}/\mu\text{s}$	170 μC
I_{RM}		45 A
R_{thJC}	per thyristor/diode; DC current per module	0.22 K/W
R_{thJK}	per thyristor/diode; DC current per module	0.11 K/W
	other values see Fig. 8/9	0.42 K/W
		0.21 K/W
d_s	Creepage distance on surface	12.7 mm
d_A	Strike distance through air	9.6 mm
a	Maximum allowable acceleration	50 m/s ²

Optional accessories for module-type MCC 95 version 1 B
 Keyed gate/cathode twin plugs with wire length = 350 mm, gate = yellow, cathode = red
 Type **ZY 200L** (L = Left for pin pair 4/5) } UL 758, style 1385,
 Type **ZY 200R** (R = right for pin pair 6/7) } CSA class 5851, guide 460-1-1

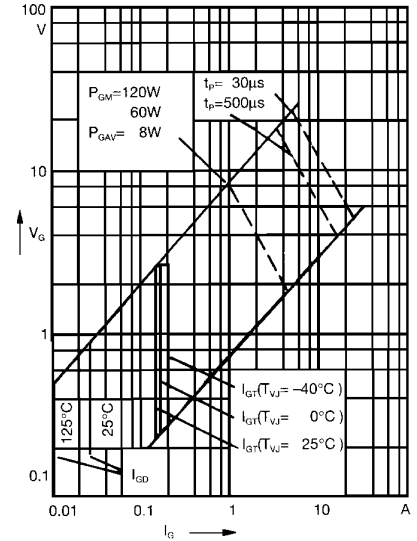


Fig. 1 Gate trigger characteristics

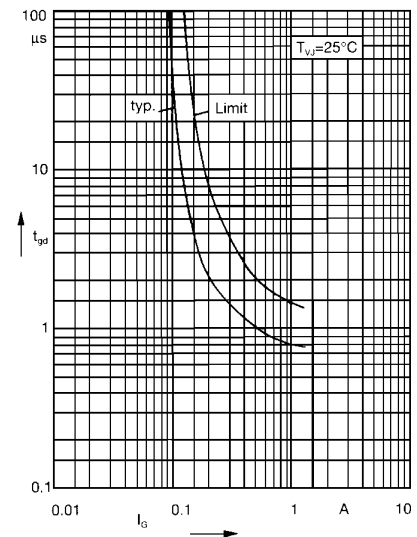
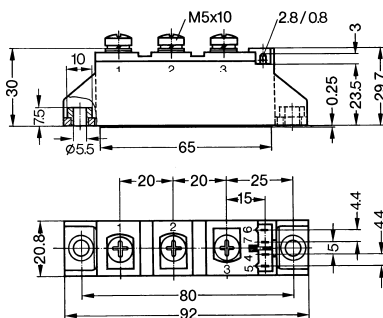


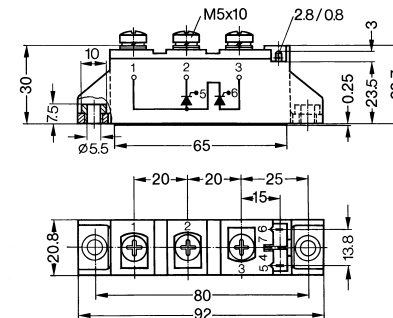
Fig. 2 Gate trigger delay time

Dimensions in mm (1 mm = 0.0394")

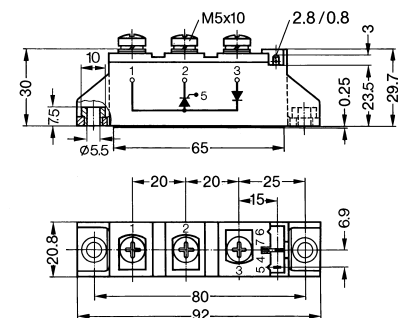
MCC / MCD Version 1 B



MCC Version 8 B



MCD Version 8 B



Version 1 or 8 without B in typ designation = without insert in mounting holes

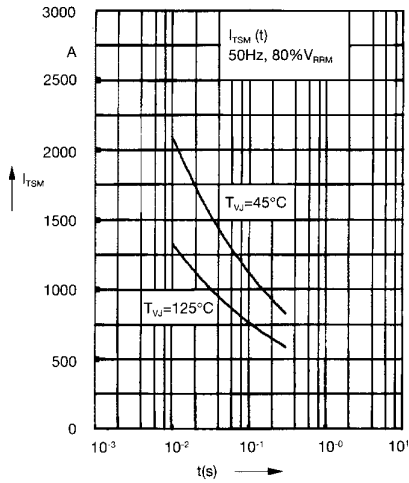


Fig. 3 Surge overload current
 I_{TSM} , I_{FSM} : Crest value, t : duration

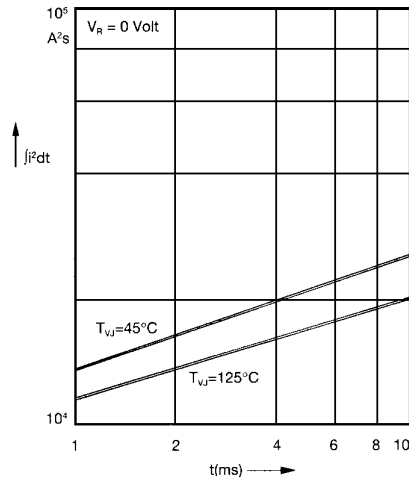


Fig. 4 $\int j^2 dt$ versus time (1-10 ms)

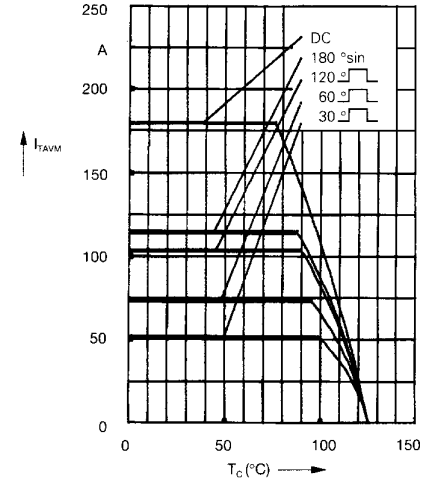


Fig. 4a Maximum forward current at case temperature

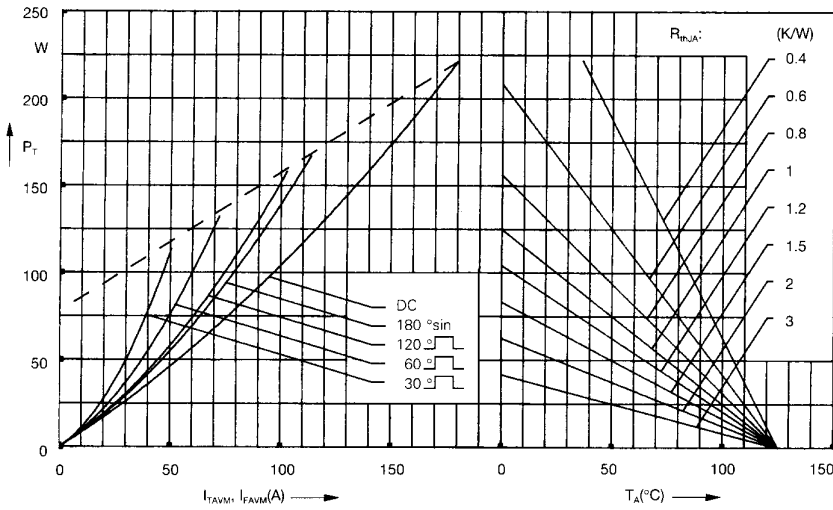


Fig. 5 Power dissipation versus on-state current and ambient temperature (per thyristor or diode)

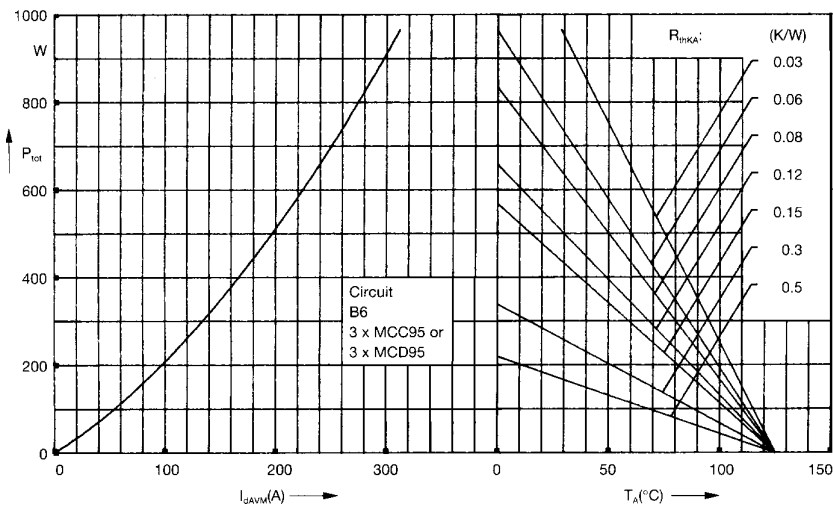


Fig. 6 Three phase rectifier bridge: Power dissipation versus direct output current and ambient temperature

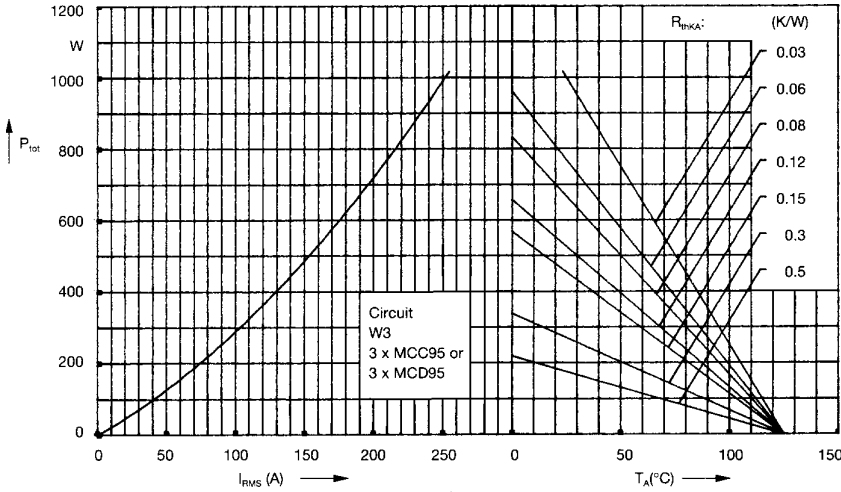


Fig. 7 Three phase AC-controller:
Power dissipation versus RMS
output current and ambient
temperature

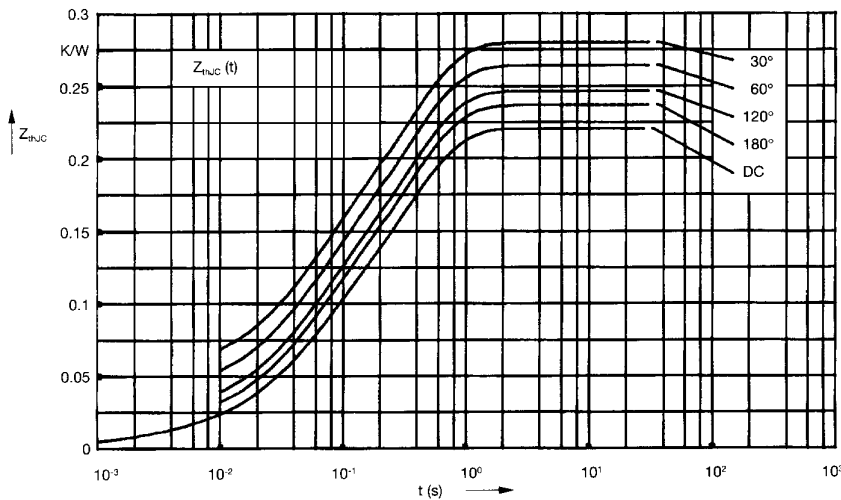


Fig. 8 Transient thermal impedance
junction to case (per thyristor or
diode)

R_{thJC} for various conduction angles d:

d	R_{thJC} (K/W)
DC	0.22
180°	0.23
120°	0.25
60°	0.27
30°	0.28

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0066	0.0019
2	0.0678	0.0477
3	0.1456	0.344

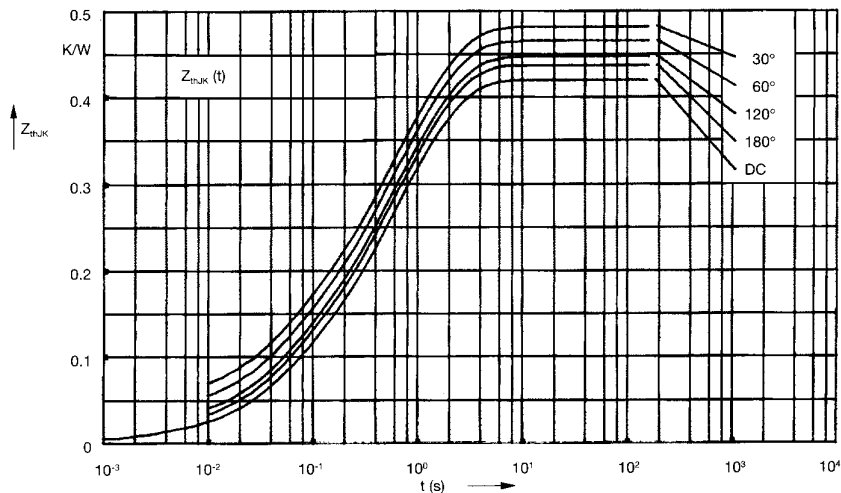


Fig. 9 Transient thermal impedance
junction to heatsink (per thyristor
or diode)

R_{thJK} for various conduction angles d:

d	R_{thJK} (K/W)
DC	0.42
180°	0.43
120°	0.45
60°	0.47
30°	0.48

Constants for Z_{thJK} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0066	0.0019
2	0.0678	0.0477
3	0.1456	0.344
4	0.2	1.32